PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JEROME D COHEN	12/21/2007
ROBERT G HAAS	12/21/2007
CHRISTOPHER L TESSLER	12/21/2007

RECEIVING PARTY DATA

Name:	INTERNATIONAL BUSINESS MACHINES CORPORATION
Street Address:	NEW ORCHARD ROAD
City:	ARMONK
State/Country:	NEW YORK
Postal Code:	10504

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12014959

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	JOSEPH PETROKAITIS

Total Attachments: 1

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PATENT

REEL: 020372 FRAME: 0076

Docket No.: FIS920070477US1

ASSIGNMENT

INVENTOR AND CITY	Whereas, we (1) Jerome D. Cohen of Poughquag, County of Dutchess and State of New York; (2) Robert G. Haas of Wappingers Falls, County of Dutchess and State of New York; and (3) Christopher L. Tessler of Campbell Hall, County of Orange and State of New York.
TITLE	have invented certain improvements in REMOVING MATERIAL FROM DEFECTIVE OPENING IN GLASS MOLD AND RELATED GLASS MOLD FOR INJECTION MOLDED SOLDER
DATES THAT INVENTORS SIGNED THE DECLARATION	and executed, respectively, a United States patent application therefor on (1) $\frac{12/2}{2/2}$, 2007, (2) $\frac{12/2}{2}$, 2007, (3) $\frac{12/2}{2}$, 2007.
of business at a interest in the sinterest in the sintere	ERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and said application and invention, and to any United States and foreign patents to be obtained therefor; for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, sign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said invention therein disclosed for the United States and foreign countries, and in all foreign countries, for priority resulting from the filing of said United States application, and we request the of Patents to issue any Letters Patent granted upon the inventions set forth in said application to sors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said we will execute all papers necessary in connection with the United States and foreign applications on to do so by IBM.
Signed and sealed	

(3) Christopher L. Tossler

on $\frac{12}{2}$, 2007

Christopher L. Tessler

RECORDED: 01/16/2008